

Electronic Patent Application Fee Transmittal

Application Number:	10509899			
Filing Date:	29-Jun-2005			
Title of Invention:	IC CHIP MOUNTING SUBSTRATE, IC CHIP MOUNTING SUBSTRATE MANUFACTURING METHOD, OPTICAL COMMUNICATION DEVICE, AND OPTICAL COMMUNICATION DEVICE MANUFACTURING METHOD			
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Attorney Docket Number:	259189US90PCT			
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Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

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Total in USD (\$)				1110